



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, Microwire, SD, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	49
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	168K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TFBGA
Supplier Device Package	100-TFBGA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4310fet100-551

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P1_8	R7	M5	H5	51	[2]	N; PU	I/O	GPIO1[1] — General purpose digital input/output pin.
							O	U1_DTR — Data Terminal Ready output for UART1.
							O	CTOUT_12 — SCTimer/PWM output 12. Match output 3 of timer 3.
							I/O	EMC_D1 — External memory data line 1.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	SD_VOLT0 — SD/MMC bus voltage select output 0.
P1_9	T7	N5	J5	52	[2]	N; PU	I/O	GPIO1[2] — General purpose digital input/output pin.
							O	U1_RTS — Request to Send output for UART1.
							O	CTOUT_11 — SCTimer/PWM output 11. Match output 3 of timer 2.
							I/O	EMC_D2 — External memory data line 2.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SD_DAT0 — SD/MMC data bus line 0.
P1_10	R8	N6	H6	53	[2]	N; PU	I/O	GPIO1[3] — General purpose digital input/output pin.
							I	U1_RI — Ring Indicator input for UART1.
							O	CTOUT_14 — SCTimer/PWM output 14. Match output 2 of timer 3.
							I/O	EMC_D3 — External memory data line 3.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SD_DAT1 — SD/MMC data bus line 1.
P1_11	T9	P8	J7	55	[2]	N; PU	I/O	GPIO1[4] — General purpose digital input/output pin.
							I	U1_CTS — Clear to Send input for UART1.
							O	CTOUT_15 — SCTimer/PWM output 15. Match output 3 of timer 3.
							I/O	EMC_D4 — External memory data line 4.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SD_DAT2 — SD/MMC data bus line 2.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P3_8	C10	C9	E7	124	[2]	N; PU	-	R — Function reserved.
							I	SPI_SSEL — Slave Select for SPI. Note that this pin in an input pin only. The SPI in master mode cannot drive the CS input on the slave. Any GPIO pin can be used for SPI chip select in master mode.
							I/O	SSP0_MOSI — Master Out Slave in for SSP0.
							I/O	SPIFI_CS — SPIFI serial flash chip select.
							I/O	GPIO5[11] — General purpose digital input/output pin.
							I/O	SSP0_SSEL — Slave Select for SSP0.
							-	R — Function reserved.
							-	R — Function reserved.
P4_0	D5	D4	-	1	[2]	N; PU	I/O	GPIO2[0] — General purpose digital input/output pin.
							O	MCOA0 — Motor control PWM channel 0, output A.
							I	NMI — External interrupt input to NMI.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD13 — LCD data.
							I/O	U3_UCLK — Serial clock input/output for USART3 in synchronous mode.
							-	R — Function reserved.
P4_1	A1	D3	-	3	[5]	N; PU	I/O	GPIO2[1] — General purpose digital input/output pin.
							O	CTOUT_1 — SCTimer/PWM output 1. Match output 3 of timer 3.
							O	LCD_VD0 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD19 — LCD data.
							O	U3_TXD — Transmitter output for USART3.
							I	ENET_COL — Ethernet Collision detect (MII interface).
							AI	ADC0_1 — ADC0 and ADC1, input channel 1. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P5_6	T13	M11	-	63	[2]	N; PU	I/O	GPIO2[15] — General purpose digital input/output pin.
							O	MCOB1 — Motor control PWM channel 1, output B.
							I/O	EMC_D10 — External memory data line 10.
							-	R — Function reserved.
							O	U1_TXD — Transmitter output for UART 1.
							O	T1_MAT2 — Match output 2 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.
P5_7	R12	N11	-	65	[2]	N; PU	I/O	GPIO2[7] — General purpose digital input/output pin.
							O	MCOA2 — Motor control PWM channel 2, output A.
							I/O	EMC_D11 — External memory data line 11.
							-	R — Function reserved.
							I	U1_RXD — Receiver input for UART 1.
							O	T1_MAT3 — Match output 3 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.
P6_0	M12	M10	H7	73	[2]	N; PU	-	R — Function reserved.
							O	I2S0_RX_MCLK — I2S receive master clock.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	I2S0_RX_SCK — Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the <i>I²S-bus specification</i> .
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P6_1	R15	P14	G5	74	[2]	N; PU	I/O	GPIO3[0] — General purpose digital input/output pin.
							O	EMC_DYCS1 — SDRAM chip select 1.
							I/O	U0_UCLK — Serial clock input/output for USART0 in synchronous mode.
							I/O	I2S0_RX_WS — Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							-	R — Function reserved.
							I	T2_CAP0 — Capture input 2 of timer 2.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P7_7	B6	D5	-	140	[5]	N; PU	I/O	GPIO3[15] — General purpose digital input/output pin.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
							-	R — Function reserved.
							O	LCD_PWR — LCD panel power enable.
							-	R — Function reserved.
							O	TRACEDATA[3] — Trace data, bit 3.
							O	ENET_MDC — Ethernet MIIM clock.
							I/O	SGPIO7 — General purpose digital input/output pin.
							AI	ADC1_6 — ADC1 and ADC0, input channel 6. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
							I/O	GPIO4[0] — General purpose digital input/output pin.
P8_0	E5	E4	-	-	[3]	N; PU	I/O	USB0_PWR_FAULT — Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							-	R — Function reserved.
							I	MCI2 — Motor control PWM channel 2, input.
							I/O	SGPIO8 — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							O	T0_MAT0 — Match output 0 of timer 0.
							I/O	GPIO4[1] — General purpose digital input/output pin.
P8_1	H5	G4	-	-	[3]	N; PU	O	USB0_IND1 — USB0 port indicator LED control output 1.
							-	R — Function reserved.
							I	MCI1 — Motor control PWM channel 1, input.
							I/O	SGPIO9 — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							O	T0_MAT1 — Match output 1 of timer 0.
							I/O	GPIO4[2] — General purpose digital input/output pin.
P8_2	K4	J4	-	-	[3]	N; PU	O	USB0_IND0 — USB0 port indicator LED control output 0.
							-	R — Function reserved.
							I	MCI0 — Motor control PWM channel 0, input.
							I/O	SGPIO10 — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							O	T0_MAT2 — Match output 2 of timer 0.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_4	T2	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
							I/O	EMC_D18 — External memory data line 18.
							-	R — Function reserved.
							I/O	GPIO6[18] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO8 — General purpose digital input/output pin.
PD_5	P6	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_9 — SCTimer/PWM output 9. Match output 3 of timer 3.
							I/O	EMC_D19 — External memory data line 19.
							-	R — Function reserved.
							I/O	GPIO6[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO9 — General purpose digital input/output pin.
PD_6	R6	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
							I/O	EMC_D20 — External memory data line 20.
							-	R — Function reserved.
							I/O	GPIO6[20] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO10 — General purpose digital input/output pin.
PD_7	T6	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_5 — SCTimer/PWM input 5. Capture input 2 of timer 2.
							I/O	EMC_D21 — External memory data line 21.
							-	R — Function reserved.
							I/O	GPIO6[21] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO11 — General purpose digital input/output pin.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_8	P8	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_6 — SCTimer/PWM input 6. Capture input 1 of timer 3.
							I/O	EMC_D22 — External memory data line 22.
							-	R — Function reserved.
							I/O	GPIO6[22] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPIO12 — General purpose digital input/output pin.
PD_9	T11	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_13 — SCTimer/PWM output 13. Match output 3 of timer 3.
							I/O	EMC_D23 — External memory data line 23.
							-	R — Function reserved.
							I/O	GPIO6[23] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPIO13 — General purpose digital input/output pin.
PD_10	P11	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_1 — SCTimer/PWM input 1. Capture input 1 of timer 0. Capture input 1 of timer 2.
							O	EMC_BLS3 — LOW active Byte Lane select signal 3.
							-	R — Function reserved.
							I/O	GPIO6[24] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PD_11	N9	M7	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							O	EMC_CS3 — LOW active Chip Select 3 signal.
							-	R — Function reserved.
							I/O	GPIO6[25] — General purpose digital input/output pin.
							I/O	USB1_ULPI_D0 — ULPI link bidirectional data line 0.
							O	CTOUT_14 — SCTimer/PWM output 14. Match output 2 of timer 3.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PF_3	E10	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	U3_RXD — Receiver input for USART3.
							I/O	SSP0_MOSI — Master Out Slave in for SSP0.
							-	R — Function reserved.
							I/O	GPIO7[18] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO2 — General purpose digital input/output pin.
							-	R — Function reserved.
PF_4	D10	D6	H4	120	[2]	O; PU	I/O	SSP1_SCK — Serial clock for SSP1.
							I	GP_CLKIN — General-purpose clock input to the CGU.
							O	TRACECLK — Trace clock.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	I2S0_TX_MCLK — I2S transmit master clock.
							I/O	I2S0_RX_SCK — I2S receive clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I ² S-bus specification.
PF_5	E9	-	-	-	[5]	N; PU	-	R — Function reserved.
							I/O	U3_UCLK — Serial clock input/output for USART3 in synchronous mode.
							I/O	SSP1_SSEL — Slave Select for SSP1.
							O	TRACEDATA[0] — Trace data, bit 0.
							I/O	GPIO7[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO4 — General purpose digital input/output pin.
							-	R — Function reserved.
							AI	ADC1_4 — ADC1 and ADC0, input channel 4. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
Clock pins								
CLK0	N5	M4	K3	45	[4]	O; PU	O	EMC_CLK0 — SDRAM clock 0.
							O	CLKOUT — Clock output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SD_CLK — SD/MMC card clock.
							O	EMC_CLK01 — SDRAM clock 0 and clock 1 combined.
							I/O	SSP1_SCK — Serial clock for SSP1.
							I	ENET_TX_CLK (ENET_REF_CLK) — Ethernet Transmit Clock (MII interface) or Ethernet Reference Clock (RMII interface).
CLK1	T10	-	-	-	[4]	O; PU	O	EMC_CLK1 — SDRAM clock 1.
							O	CLKOUT — Clock output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	CGU_OUT0 — CGU spare clock output 0.
							-	R — Function reserved.
							O	I2S1_TX_MCLK — I2S1 transmit master clock.
CLK2	D14	P10	K6	99	[4]	O; PU	O	EMC_CLK3 — SDRAM clock 3.
							O	CLKOUT — Clock output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SD_CLK — SD/MMC card clock.
							O	EMC_CLK23 — SDRAM clock 2 and clock 3 combined.
							O	I2S0_TX_MCLK — I2S transmit master clock.
							I/O	I2S1_RX_SCK — Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I ² S-bus specification.
CLK3	P12	-	-	-	[4]	O; PU	O	EMC_CLK2 — SDRAM clock 2.
							O	CLKOUT — Clock output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	CGU_OUT1 — CGU spare clock output 1.
							-	R — Function reserved.
							I/O	I2S1_RX_SCK — Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I ² S-bus specification.

7. Functional description

7.1 Architectural overview

The ARM Cortex-M4 includes three AHB-Lite buses: the system bus, the I-CODE bus, and the D-code bus. The I-CODE and D-code core buses allow for concurrent code and data accesses from different slave ports.

The LPC4350/30/20/10 use a multi-layer AHB matrix to connect the ARM Cortex-M4 buses and other bus masters to peripherals in a flexible manner that optimizes performance by allowing peripherals that are on different slaves ports of the matrix to be accessed simultaneously by different bus masters.

An ARM Cortex-M0 co-processor is included in the LPC4350/30/20/10, capable of off-loading the main ARM Cortex-M4 application processor. Most peripheral interrupts are connected to both processors. The processors communicate with each other via an interprocessor communication protocol.

7.2 ARM Cortex-M4 processor

The ARM Cortex-M4 CPU incorporates a 3-stage pipeline, uses a Harvard architecture with separate local instruction and data buses as well as a third bus for peripherals, and includes an internal prefetch unit that supports speculative branching. The ARM Cortex-M4 supports single-cycle digital signal processing and SIMD instructions. A hardware floating-point processor is integrated in the core. The processor includes an NVIC with up to 53 interrupts.

7.3 ARM Cortex-M0 co-processor

The ARM Cortex-M0 is a general purpose, 32-bit microprocessor, which offers high performance and very low-power consumption. The ARM Cortex-M0 co-processor uses a 3-stage pipeline von-Neumann architecture and a small but powerful instruction set providing high-end processing hardware. In LPC43x0, the Cortex-M0 coprocessor hardware multiply is implemented as a 32-cycle iterative multiplier. The co-processor incorporates an NVIC with 32 interrupts.

7.4 Interprocessor communication

The ARM Cortex-M4 and ARM Cortex-M0 interprocessor communication is based on using shared SRAM as mailbox and one processor raising an interrupt on the other processor's NVIC, for example after it has delivered a new message in the mailbox. The receiving processor can reply by raising an interrupt on the sending processor's NVIC to acknowledge the message.

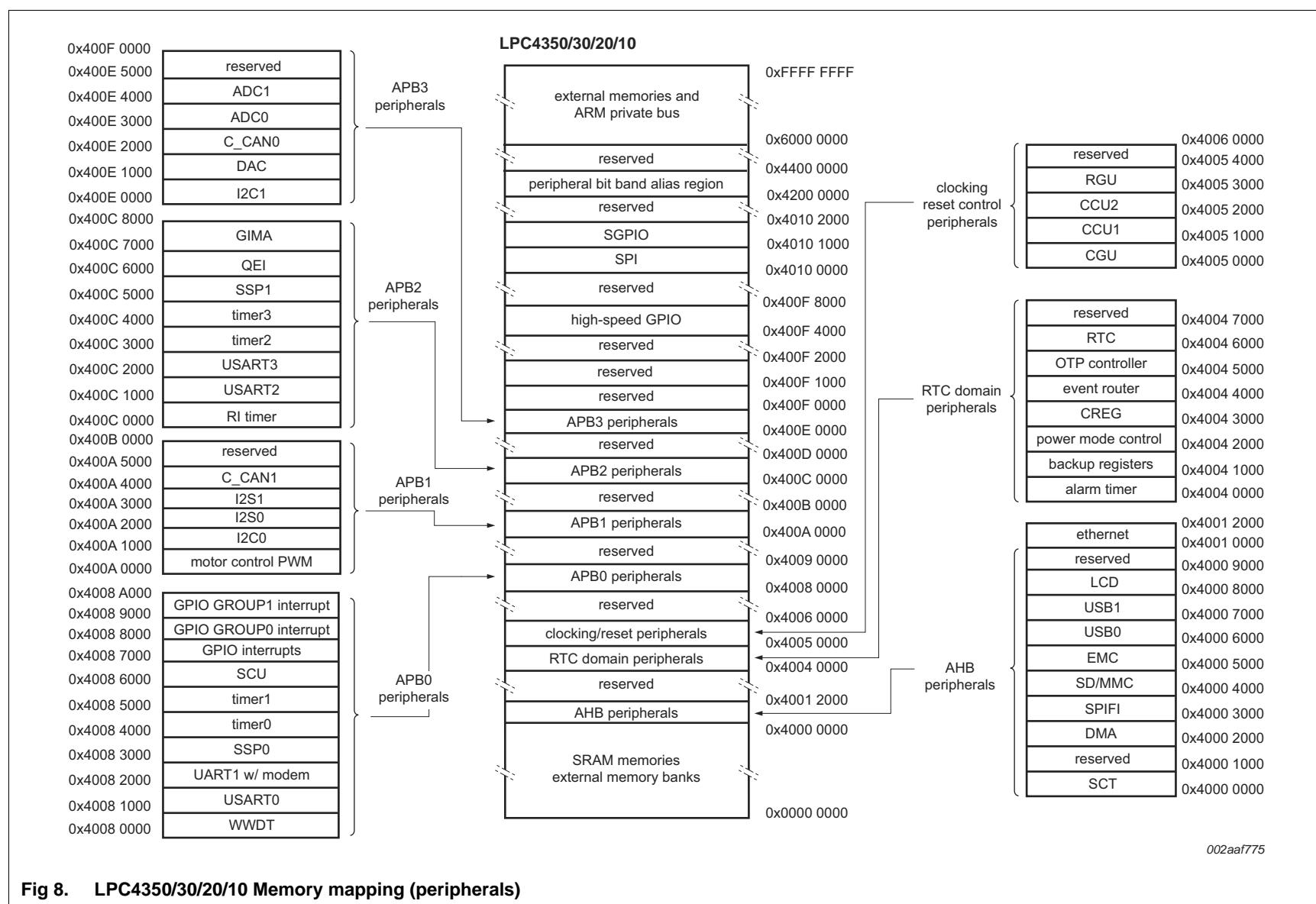
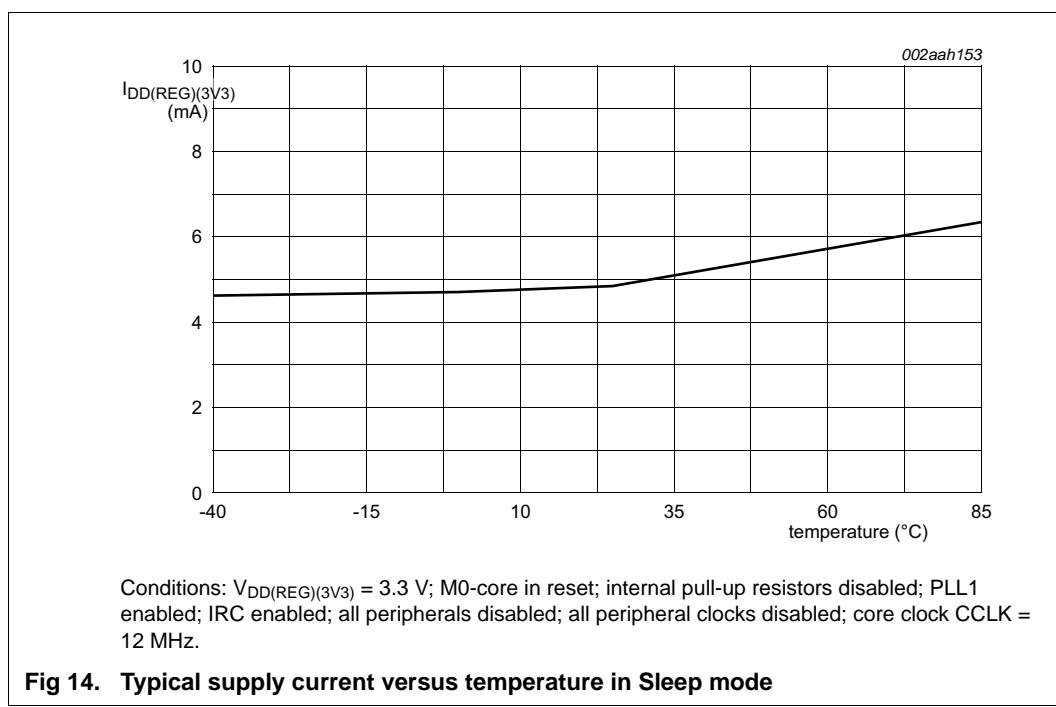
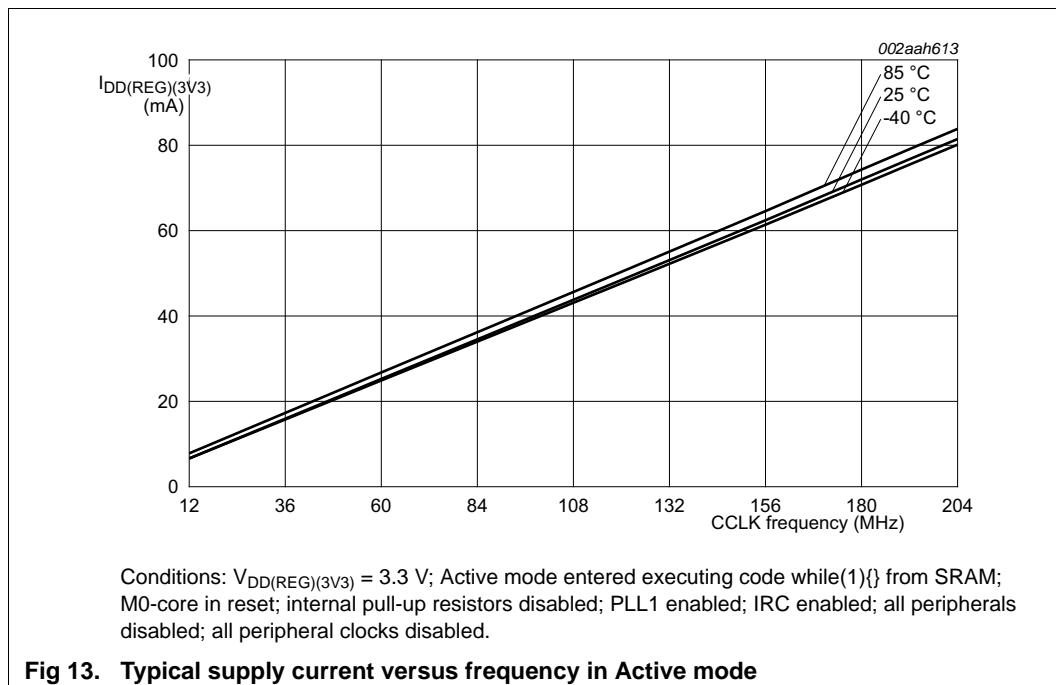
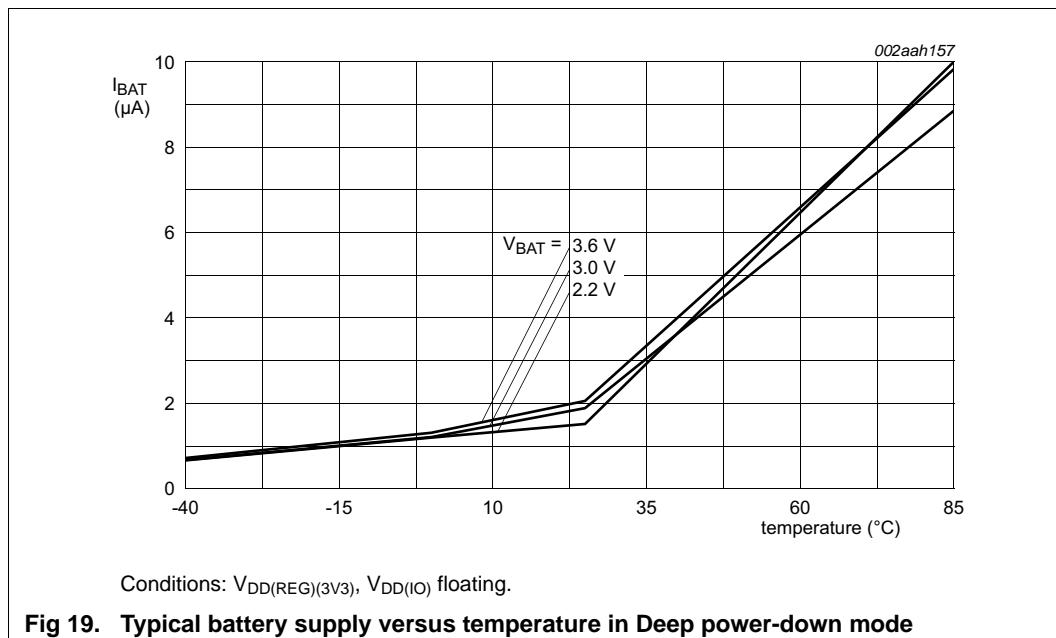


Fig 8. LPC4350/30/20/10 Memory mapping (peripherals)





10.2 Peripheral power consumption

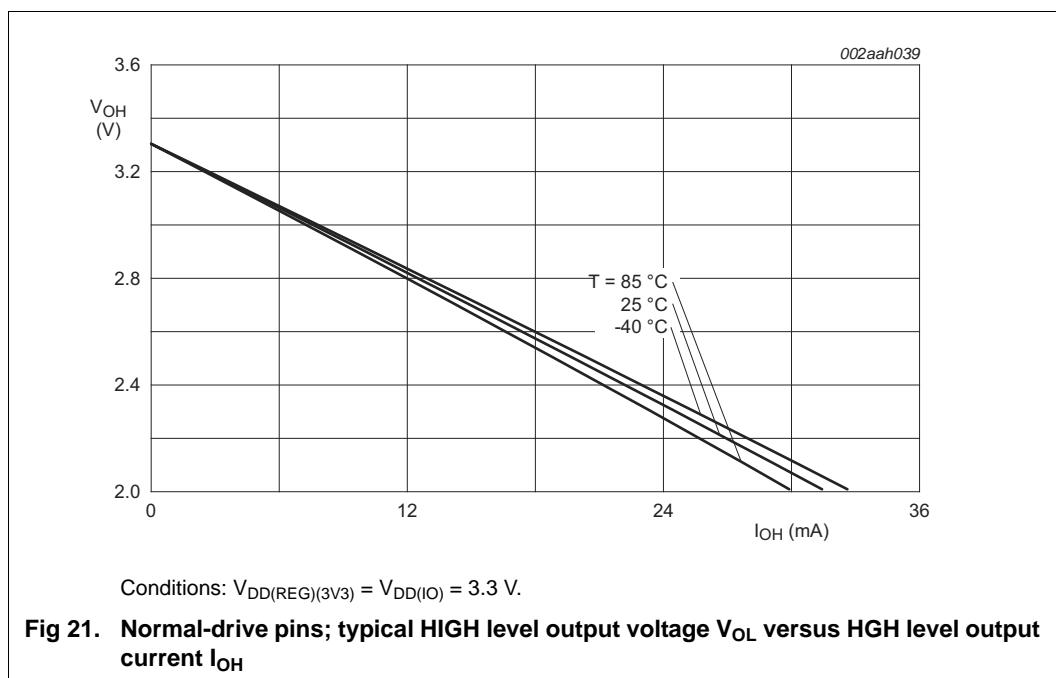
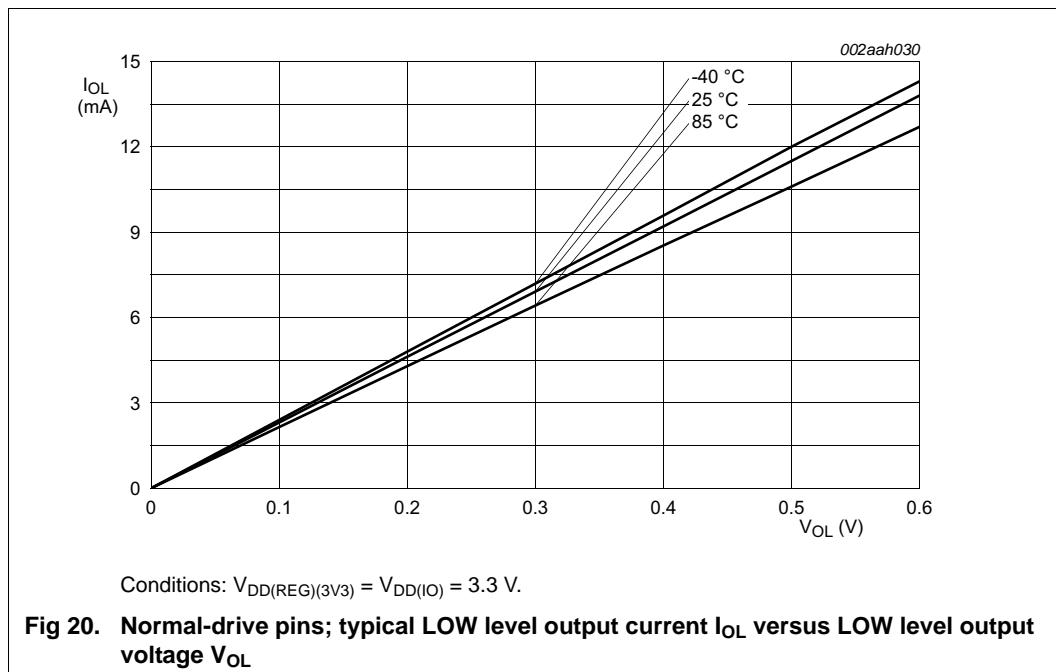
The typical power consumption at $T = 25^{\circ}\text{C}$ for each individual peripheral is measured as follows:

1. Enable all branch clocks and measure the current $I_{DD(\text{REG})}(3\text{V3})$.
2. Disable the branch clock to the peripheral to be measured and keep all other branch clocks enabled.
3. Calculate the difference between measurement 1 and 2. The result is the peripheral power consumption.

Table 11. Peripheral power consumption

Peripheral	Branch clock	$I_{DD(\text{REG})}(3\text{V3})$ in mA	
		Branch clock frequency = 48 MHz	Branch clock frequency = 96 MHz
M0 core	CLK_M4_M0APP	3.3	6.6
I2C1	CLK_APB3_I2C1	0.01	0.02
I2C0	CLK_APB1_I2C0	0.02	0.01
DAC	CLK_APB3_DAC	0.01	0.02
ADC0	CLK_APB3_ADC0	0.05	0.05
ADC1	CLK_APB3_ADC1	0.04	0.04
CAN0	CLK_APB3_CAN0	0.17	0.17
CAN1	CLK_APB1_CAN1	0.17	0.17
MOTOCON	CLK_APB1_MOTOCON	0.05	0.05
I2S	CLK_APB1_I2S	0.11	0.11
SPIFI	CLK_SPIFI, CLK_M4_SPIFI	0.95	1.85
GPIO	CLK_M4_GPIO	0.66	1.31

10.4 Electrical pin characteristics



11.12 SPI interface

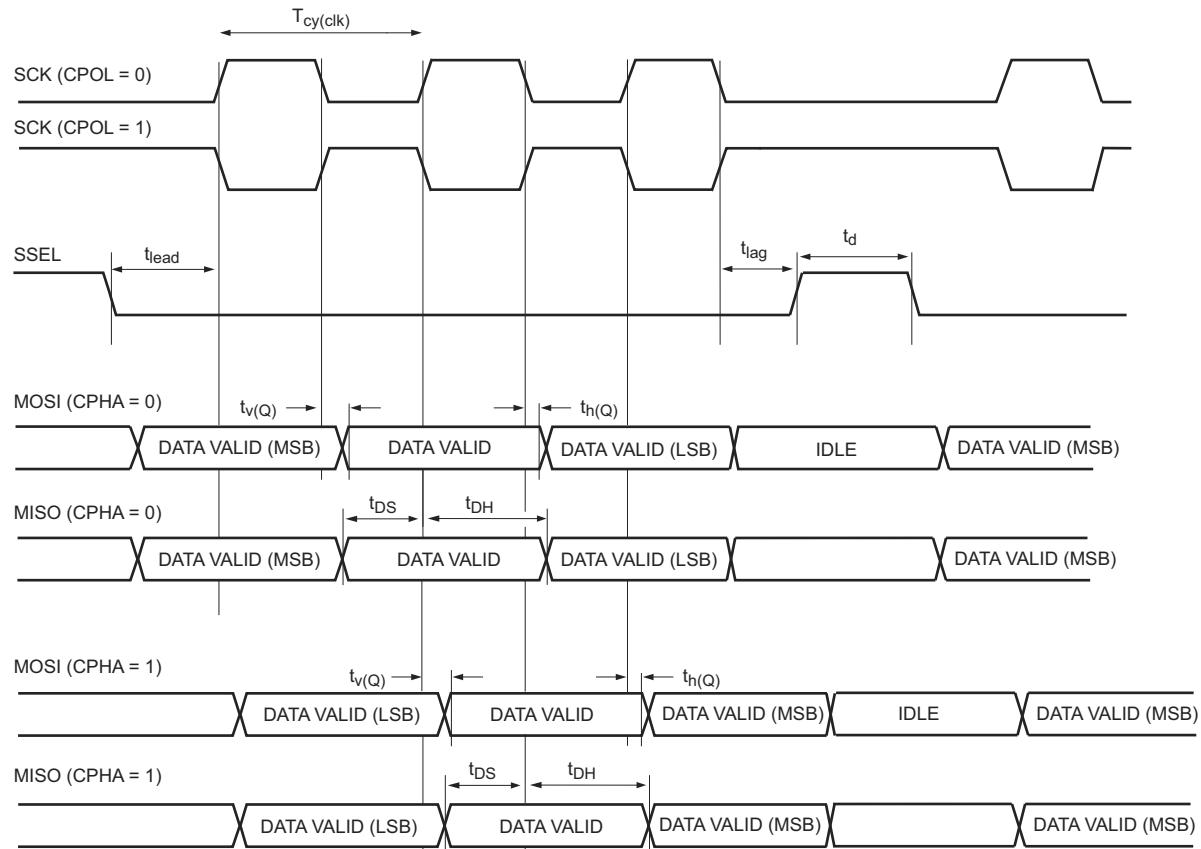
Table 25. Dynamic characteristics: SPI

$T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$; $2.2 \text{ V} \leq V_{DD(\text{REG})}(3V3) \leq 3.6 \text{ V}$; $2.7 \text{ V} \leq V_{DD(\text{IO})} \leq 3.6 \text{ V}$. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$T_{cy(\text{PCLK})}$	PCLK cycle time			5			ns
$T_{cy(\text{clk})}$	clock cycle time		[1]	40	-	-	ns
Master							
t_{DS}	data set-up time			7.2	-	-	ns
t_{DH}	data hold time			0	-	-	ns
$t_{V(Q)}$	data output valid time			-	-	3.7	ns
$t_{h(Q)}$	data output hold time			-	-	1.2	ns
Slave							
t_{DS}	data set-up time			1.2	-	-	ns
t_{DH}	data hold time			$3 \times T_{cy(\text{PCLK})} + 0.54$	-	-	ns
$t_{V(Q)}$	data output valid time			-	-	$3 \times T_{cy(\text{PCLK})} + 9.7$	ns
$t_{h(Q)}$	data output hold time			-	-	$2 \times T_{cy(\text{PCLK})} + 7.1$	ns

[1] $T_{cy(\text{clk})} = 8/\text{BASE_SPI_CLK}$. $T_{cy(\text{PCLK})} = 1/\text{BASE_SPI_CLK}$.

11.13 SSP/SPI timing diagrams



aaa-013462

Fig 31. SSP_master mode timing (SPI mode)

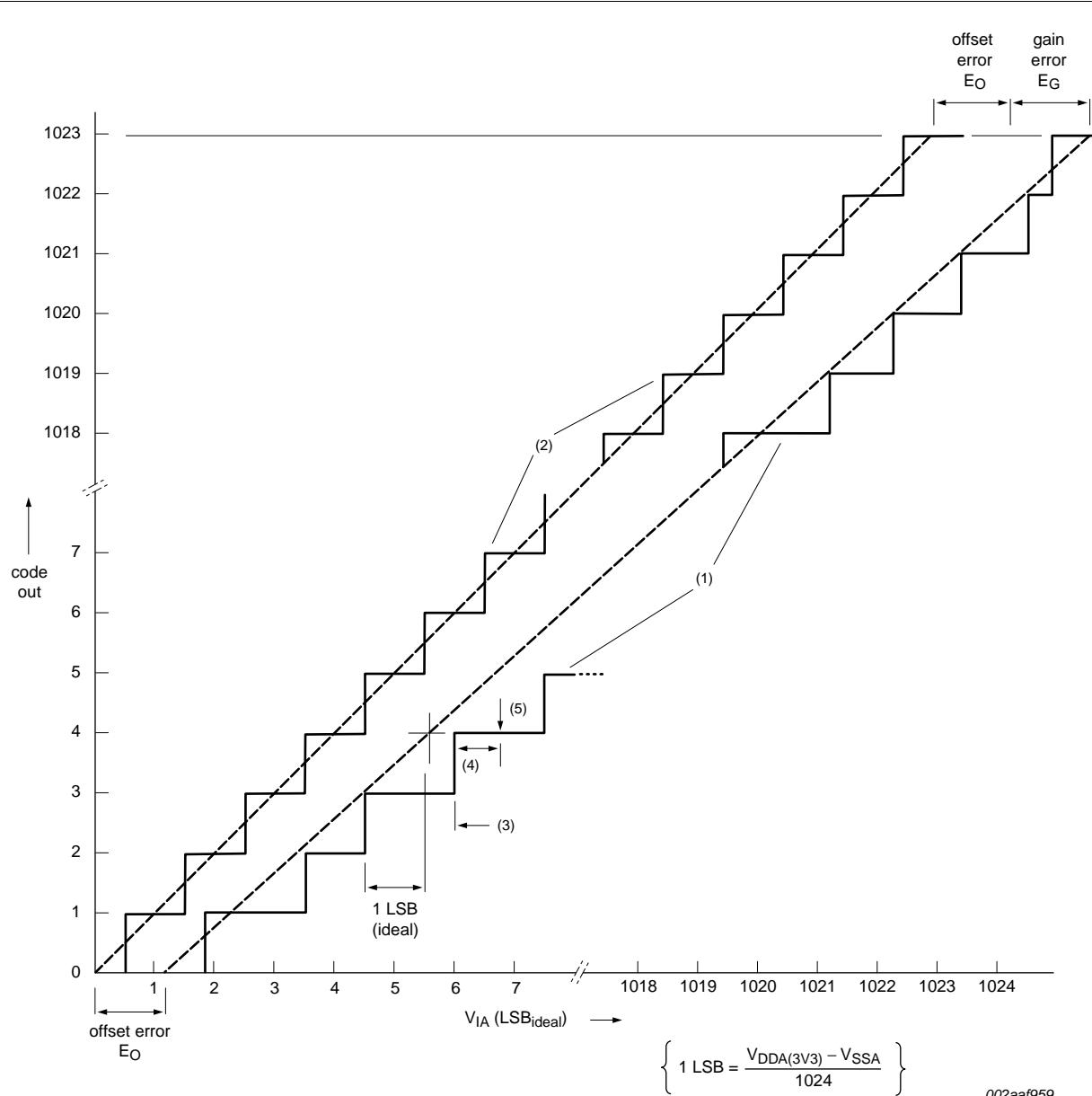
12. ADC/DAC electrical characteristics

Table 36. ADC characteristics

$V_{DDA(3V3)}$ over specified ranges; $T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$; unless otherwise specified.

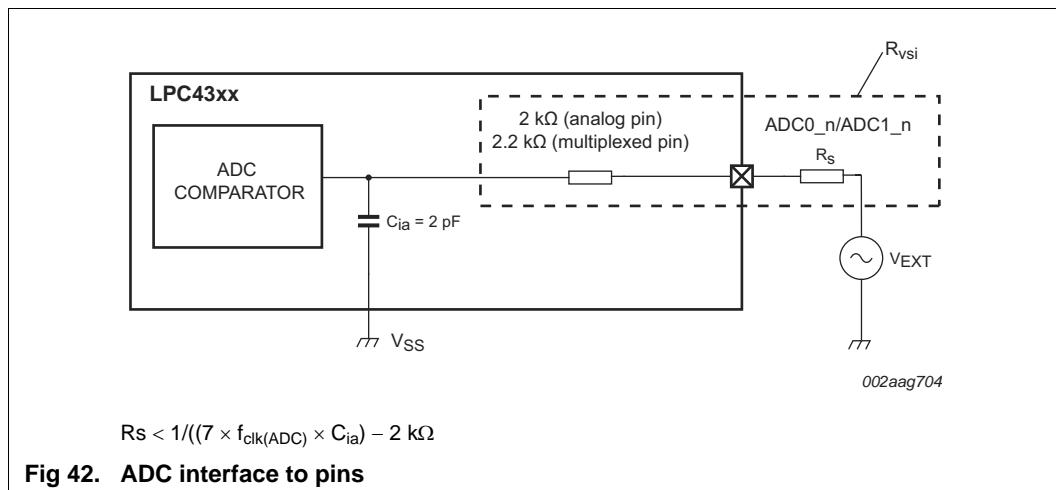
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IA}	analog input voltage		0	-	$V_{DDA(3V3)}$	V
C_{ia}	analog input capacitance		-	-	2	pF
E_D	differential linearity error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[1][2]	-	± 0.8	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$		-	± 1.0	LSB
$E_{L(adj)}$	integral non-linearity	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[3]	-	± 0.8	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$		-	± 1.5	LSB
E_O	offset error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[4]	-	± 0.15	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$		-	± 0.15	LSB
E_G	gain error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[5]	-	± 0.3	%
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$		-	± 0.35	%
E_T	absolute error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[6]	-	± 3	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$		-	± 4	LSB
R_{vsi}	voltage source interface resistance	see Figure 42	-	-	$1/(7 \times f_{clk(ADC)} \times C_{ia})$	kΩ
R_i	input resistance		[7][8]	-	1.2	MΩ
$f_{clk(ADC)}$	ADC clock frequency		-	-	4.5	MHz
f_s	sampling frequency	10-bit resolution; 11 clock cycles	-	-	400	kSamples/s
		2-bit resolution; 3 clock cycles			1.5	MSamples/s

- [1] The ADC is monotonic, there are no missing codes.
- [2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See [Figure 41](#).
- [3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See [Figure 41](#).
- [4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See [Figure 41](#).
- [5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See [Figure 41](#).
- [6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See [Figure 41](#).
- [7] $T_{amb} = 25^{\circ}\text{C}$.
- [8] Input resistance R_i depends on the sampling frequency f_s : $R_i = 2 \text{ k}\Omega + 1 / (f_s \times C_{ia})$.



- (1) Example of an actual transfer curve.
- (2) The ideal transfer curve.
- (3) Differential linearity error (E_D).
- (4) Integral non-linearity ($E_{L(\text{adj})}$).
- (5) Center of a step of the actual transfer curve.

Fig 41. 10-bit ADC characteristics

**Table 37. DAC characteristics** $V_{DDA(3V3)}$ over specified ranges; $T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$; unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
E_D	differential linearity error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[1]	-	± 0.8	-	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$	-	± 1.0	-	-	LSB
$E_{L(adj)}$	integral non-linearity	code = 0 to 975	[1]	-	± 1.0	-	LSB
		$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	-	± 1.0	-	-	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$	-	± 1.5	-	-	LSB
E_O	offset error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[1]	-	± 0.8	-	LSB
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$	-	± 1.0	-	-	LSB
E_G	gain error	$2.7 \text{ V} \leq V_{DDA(3V3)} \leq 3.6 \text{ V}$	[1]	-	± 0.3	-	%
		$2.2 \text{ V} \leq V_{DDA(3V3)} < 2.7 \text{ V}$	-	± 1.0	-	-	%
C_L	load capacitance		-	-	200	pF	
R_L	load resistance		1	-	-	kΩ	
t_s	settling time		[2]	0.4		μσ	

[1] In the DAC CR register, bit BIAS = 0 (see the *LPC43xx user manual*).

[2] Settling time is calculated within 1/2 LSB of the final value.

Table 40. LCD panel connections for TFT panels ...continued

External pin	TFT 12 bit (4:4:4 mode)		TFT 16 bit (5:6:5 mode)		TFT 16 bit (1:5:5:5 mode)		TFT 24 bit	
	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function
LCD_VD0	-	-	-	-	-	-	P4_1	REDO
LCD_LP	P7_6	LCDLP	P7_6	LCDLP	P7_6	LCDLP	P7_6	LCDLP
LCD_ENAB	P4_6 /LCDM	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM
LCD_FP	P4_5	LCDFP	P4_5	LCDFP	P4_5	LCDFP	P4_5	LCDFP
LCD_DCLK	P4_7	LCDDCLK	P4_7	LCDDCLK	P4_7	LCDDCLK	P4_7	LCDDCLK
LCD_LE	P7_0	LCDLE	P7_0	LCDLE	P7_0	LCDLE	P7_0	LCDLE
LCD_PWR	P7_7	LCDPWR	P7_7	LCDPWR	P7_7	LCDPWR	P7_7	LCDPWR
GP_CLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN

13.2 Crystal oscillator

The crystal oscillator is controlled by the XTAL_OSC_CTRL register in the CGU (see *LPC43xx user manual*).

The crystal oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the PLL.

The oscillator can operate in one of two modes: slave mode and oscillation mode.

- In slave mode, couple the input clock signal with a capacitor of 100 pF (C_C in [Figure 43](#)), with an amplitude of at least 200 mV (RMS). The XTAL2 pin in this configuration can be left unconnected.
- External components and models used in oscillation mode are shown in [Figure 44](#), and in [Table 41](#) and [Table 42](#). Since the feedback resistance is integrated on chip, only a crystal and the capacitances CX1 and CX2 need to be connected externally in case of fundamental mode oscillation L, CL and RS represent the fundamental frequency). The capacitance C_P in [Figure 44](#) represents the parallel package capacitance and must not be larger than 7 pF. Parameters FC, CL, RS and CP are supplied by the crystal manufacturer.

Table 41. Recommended values for $C_{X1/X2}$ in oscillation mode (crystal and external components parameters) low frequency mode

Fundamental oscillation frequency	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
2 MHz	< 200 Ω	33 pF, 33 pF
	< 200 Ω	39 pF, 39 pF
	< 200 Ω	56 pF, 56 pF
4 MHz	< 200 Ω	18 pF, 18 pF
	< 200 Ω	39 pF, 39 pF
	< 200 Ω	56 pF, 56 pF
8 MHz	< 200 Ω	18 pF, 18 pF
	< 200 Ω	39 pF, 39 pF

14. Package outline

LBGA256: plastic low profile ball grid array package; 256 balls; body 17 x 17 x 1 mm

SOT740-2

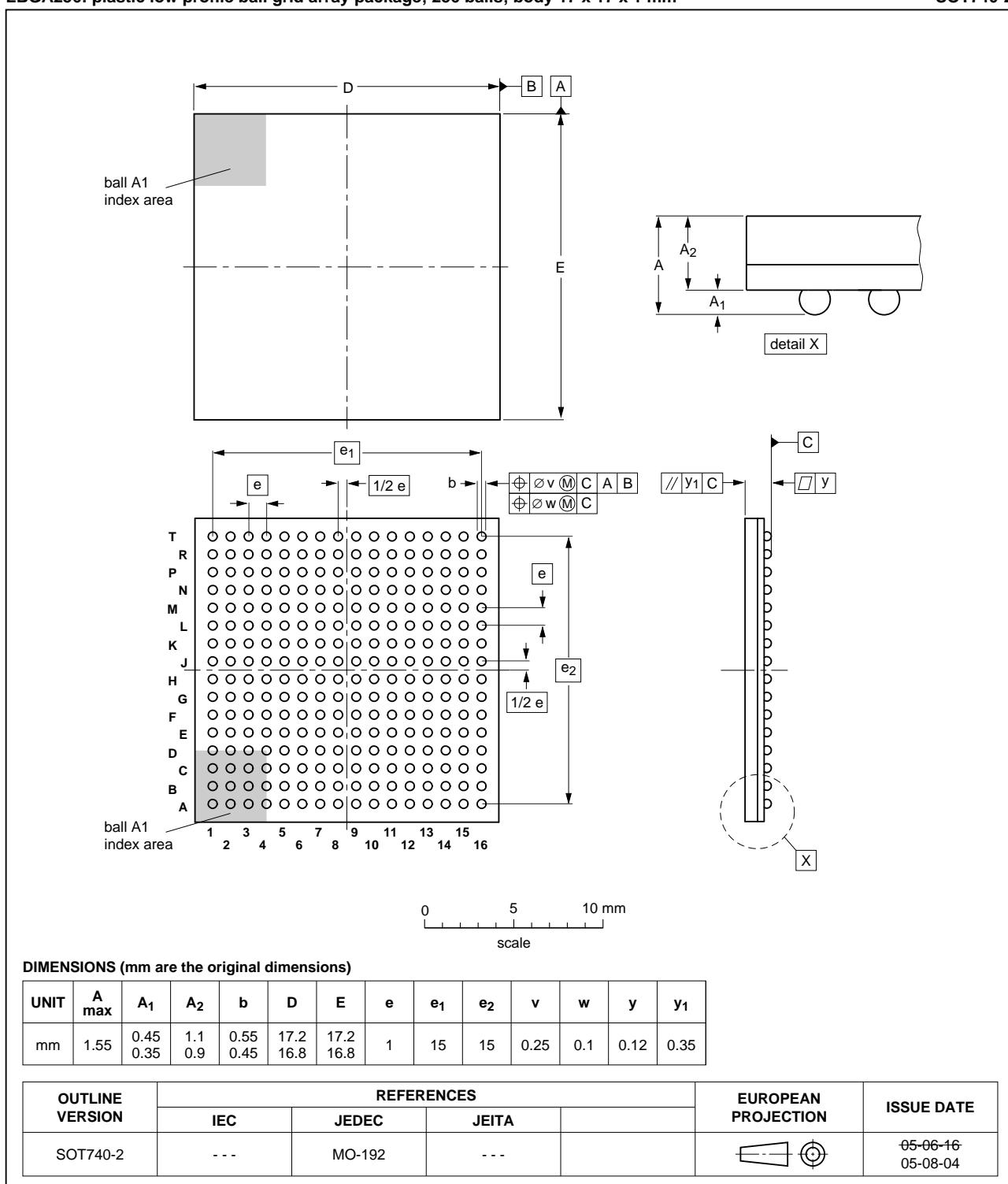


Fig 51. Package outline LBGA256 package